FS8308 Low Power PLL Frequency Synthesizer IC
Advance Information

HiMARK

Description

The FS8308 is a serial data input, phase-locked loop IC with programmable input and reference frequency dividers. When combined with a VCO, this IC becomes the core of a very low power frequency synthesizer well-suited for mobile communication applications, e.x. paging systems and family radio service (FRS). There are some features implemented in this IC, including an 18-bit programmable input frequency divider, a terminal for reference oscillator buffer output, as well as stand-by control through programming, and etc. Details are listed in the following.
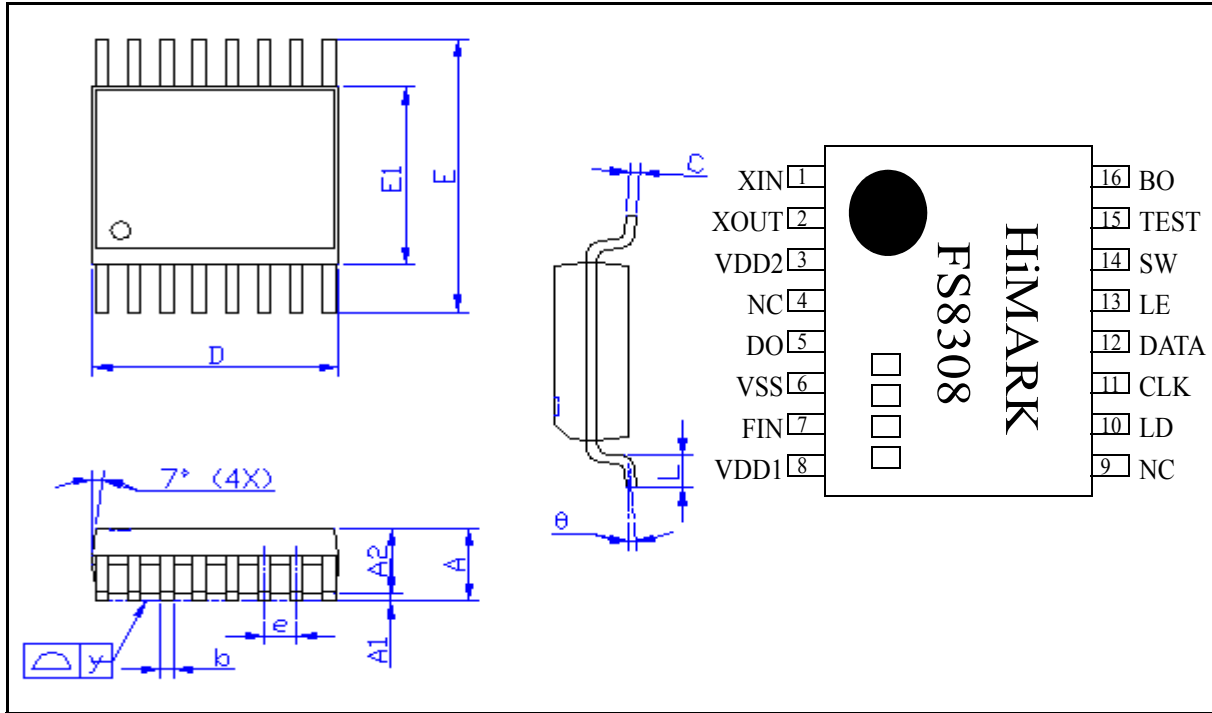
Features

◆ Up to 40 MHz external crystal oscillator reference frequency under normal condition
◆ Low current consumption ($I_{DD,total}$ typically 1.2 mA at f_{FIN} = 500 MHz and V_{DD1} = 1.0 V)
◆ With Schmitt trigger added for noise-immune programming input
◆ 18-bit programmable input frequency divider (including a ÷ 64/65 prescaler) with divide ratio range from 4032 to 262143
◆ 13-bit programmable reference frequency divider (including a ÷ 8 prescaler) with divide ratio range from 40 to 65528
◆ Optional lock detector output (*LD, $f_R/2$, $f_V/2$*)
◆ Charge pump output for passive low-pass filter
◆ Wide tuning range of charge pump output for external VCO (*V_{SS}+0.5 to V_{DD2}-0.5*)
◆ Switchover terminal for constant of loop filter or general open drain output
◆ Reference oscillator buffer output
◆ Programmable stand-by control
◆ TSSOP 16L package (0.65mm pitch)

Applications

◆ Pager
◆ Family radio service (FRS)
◆ Wireless communication system

Package and Pin Assignment: 16L, TSSOP

XIN	1		16	BO
XOUT	2		15	TEST
VDD2	3		14	SW
NC	4	HiMARK	13	LE
DO	5	FS8308	12	DATA
VSS	6		11	CLK
FIN	7		10	LD
VDD1	8		9	NC

Symbols	Dimensions in mm			Dimensions in inch		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	---	---	1.20	---	---	0.048
A1	0.05	---	0.15	0.002	---	0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19	---	0.30	0.007	---	0.012
C	0.09	---	0.20	0.004	---	0.008
D	4.90	5.00	5.10	0.193	0.197	0.201
E	---	6.40	---	---	0.252	---
E1	4.30	4.40	4.50	0.169	0.173	0.177
e	---	0.65	---	---	0.026	---
L	0.45	0.60	0.75	0.018	0.024	0.030
y	---	---	0.10	---	---	0.004
θ	$0°$	---	$8°$	$0°$	---	$8°$

Note: Tolerance $\pm$ 0.1mm unless otherwise specified

Pin Descriptions

Number	Name	I/O	Description
1	XIN	I	Reference crystal oscillator or external clock input with internally biased amplifier (any external input to XIN must be ac-coupled)
2	XOUT	O	Reference crystal oscillator or external clock output
3	VDD2	POWER	Nominal 3.0 V supply voltage
4	NC	NC	No connection
5	DO	O	Single-ended charge pump output for passive low-pass filter
6	VSS	GND	Ground
7	FIN	I	VCO frequency input with internally biased input amplifier (any external input to FIN must be ac-coupled)
8	VDD1	POWER	Nominal 1.0 V supply voltage
9	NC	NC	No connection
10	LD	O	Lock detector output (high when PLL is locked)
11	CLK	I	Shift register clock input
12	DATA	I	Serial data input
13	LE	I	Latch enable input
14	SW	O	Switchover terminal for constant of loop filter or a general open drain output
15	TEST	I	Test mode control input with internal pull-down resistor
16	BO	O	Terminal of reference crystal oscillator buffer output

Block Diagram
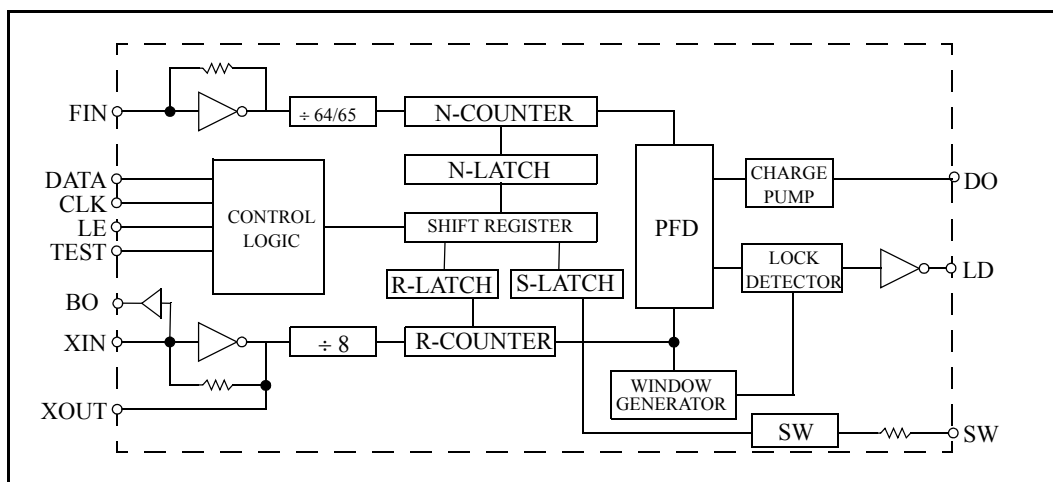
Absolute Maximum Ratings

$V_{SS} = 0$ V

Parameter	Symbol	Rating	Unit
Supply voltage	V_{DD1}	$V_{SS} - 0.3$ to $V_{SS} + 2.0$	V
	V_{DD2}	$V_{SS} - 0.3$ to $V_{SS} + 6.0$	V
Input voltage range	V_{FIN}	$V_{SS} - 0.3$ to $V_{DD} + 0.3$	V
Operating temperature range	T_{PS}	-30 to 60	ºC
Storage temperature range	T_{STG}	-40 to 125	ºC
Soldering temperature range	T_{SLD}	255	ºC
Soldering time range	t_{SLD}	10	s

Recommended Operating Conditions

$V_{SS} = 0$ V

Parameter	Symbol	Value			Unit
		min.	typ.	max.	
Supply voltage range	V_{DD1}	0.95	1.0	2.0	V
	V_{DD2}	2.4	3.0	3.6	V
Operating temperature	T_A	-30	25	60	ºC

Electrical Characteristics

(V_{DD1} = 0.95 to 2.0 V, V_{DD2} = 2.4 to 3.6 V, V_{SS} = 0 V, T_A = 0 to 60°C unless otherwise noted)

Parameter	Symbol	Condition	Value			Unit
			min.	typ.	max.	
Current consumption	$I_{DD,total}$	V_{DD1} = 1.0 V f_{FIN} = 500 MHz f_{XIN} =24 MHz		1.2	1.5	mA
Standby current consumption	$I_{DD,standby}$	PS="H"			10	μA
FIN operating frequency range	f_{FIN}	P_{FIN} = -15dBm V_{DD1} = 1.0 V, PS="L"	20		500	MHz
XIN operating frequency range	f_{XIN}	V_{DD1} = 1.0 V	7		40	MHz
FIN input voltage swing	P_{FIN}		-15			dBm
XIN input voltage swing	V_{XIN}		0.3			V_{pk-pk}
CLK, DATA, LE logic LOW input voltage	V_{IL}				0.3	V
CLK, DATA, LE logic HIGH input voltage	V_{IH}		V_{DD}-0.3			V
XIN logic LOW input current	$I_{IL,XIN}$	V_{IL} = 0 V			10	μA
XIN logic HIGH input current	$I_{IH,XIN}$	V_{IH} = V_{DD1}			10	μA
FIN logic LOW input current	$I_{IL,FIN}$	V_{IL} = 0 V			60	μA
FIN logic HIGH input current	$I_{IH,FIN}$	V_{IH} = V_{DD1}			60	μA
Charge Pump Drive Current	I_{DO}	V_{DD2} = 3.0V, V_{DO} = 1.5V		1.0		mA
Charge Pump Sink Current	I_{DO}	V_{DD2} = 3.0V, V_{DO} = 1.5V		1.0		mA
LD, FV, FR logic LOW output current	I_{OL}	V_{OL} = 0.4 V	0.1			mA
LD, FV, FR logic HIGH output current	I_{OH}	V_{OH} = V_{DD2} − 0.4 V	0.1			mA
SW logic LOW output current	$I_{SW,OFF}$	SW = 'L' V_{SW} = V_{DD2} = 3.0V			10	μA
SW logic HIGH output current	$I_{SW,ON}$	SW = 'H' V_{SW} = V_{DD2} = 3.0V		2.8		mA
DATA to CLK setup time	t_{SU1}		2			μs
CLK to LE setup time	t_{SU2}		2			μs
Hold time	t_{HOLD}		2			μs

Functional Description

Programmable Input Frequency Divider

The VCO input to the FIN pin is divided by the programmable divider and then internally output to the phase/frequency detector (PFD) as f_V. The programmable input frequency divider consists of a $\div 64/65$ ($P/P+1$) dual-modulus prescaler in prior to a 18-bit (N) counter, which is further comprised of a 6-bit swallow (A) counter, and a 12-bit main (B) counter. The total divide ratio, N, is related to values for P, A, and B through the relation

$$N = (P+1) \times A + P \times (B-A) = P \times B + A,$$

with $B \geq A$. The minimum available programmable divisor for continuous counting is given by $P \times (P-1) = 64 \times 63 = 4032$, and the valid total divide ratio range for the input divider is $M = 4032 \text{ to } 262143$.

Take N=10000 for example, since P=64 and hence that B=156 and A=16. Therefore, the binary codes of B and A should be 0000 1001 1100 and 010000, respectively. An alternative approach is to translate the decimal N into binary code directly. And then just take the last 6-bit as A and the remaining 12-bit as B. By far the binary code of N=10000 is 00 0010 0111 0001 0000. One can get the same result as the former method.

Programmable Reference Frequency Divider

The crystal oscillator output is divided by the programmable divider and then internally output to the PFD as f_R. The programmable reference frequency divider consists of a fixed $\div 8$ (S) prescaler and a 13-bit reference (R) counter. The total divide ratio, T, is related to values for S and R through the relation

$$T = S \times R = 8 \times R.$$

The usable divisior range of the reference counter is $R = 5 \text{ to } 8191$ and therefore, the valid total divide ratio range for the reference divider is $T = 40 \text{ to } 65528$ (in steps of 8.)

Serial Input Data Format

The divsors of the input and reference dividers are input using a 20-bit serial interface consisting of separate clock (CLK), data (DATA), and latch enable (LE) lines. The format of the serial data is shown in Fig. 1. The data on the DATA line is written to the shift register on the rising edge of the CLK signal and is input with MSB first. The last two bits are recognized as the latch select control bits. Data on the DATA line should be changed on the falling edge of CLK, and LE should be held low while data is being written to the shift register. Data is transferred from the shift register to either one of the frequency divider latches or the optional control latch when LE is set high. When the latch select control bits are set high-low or low-low, data is loaded to the 18-bit *N*-counter latch, and when the latch select control bits are set high-high, the 2 MSBs are ignored, the next 13 data bits are loaded to the 13-bit *R*-counter latch and the remaining 3 LSBs are used to control testing modes and should be set as follows for normal operation: R14 = high, R15 = low, R16 = low. To disable LD output (*i.e.* set LD low), R14 should be set low. When the latch select control bits are set low-high, the 2 MSBs are recognized as PS and SW, which are used as stand-by control and open drain output control, respectively. The detail of two control bits setting is summarized in Table 1. In normal work condition, PS is set to low. When PS is programmed to high, it will enter stand-by mode.

Serial input data timing waveforms are shown in Fig. 2.
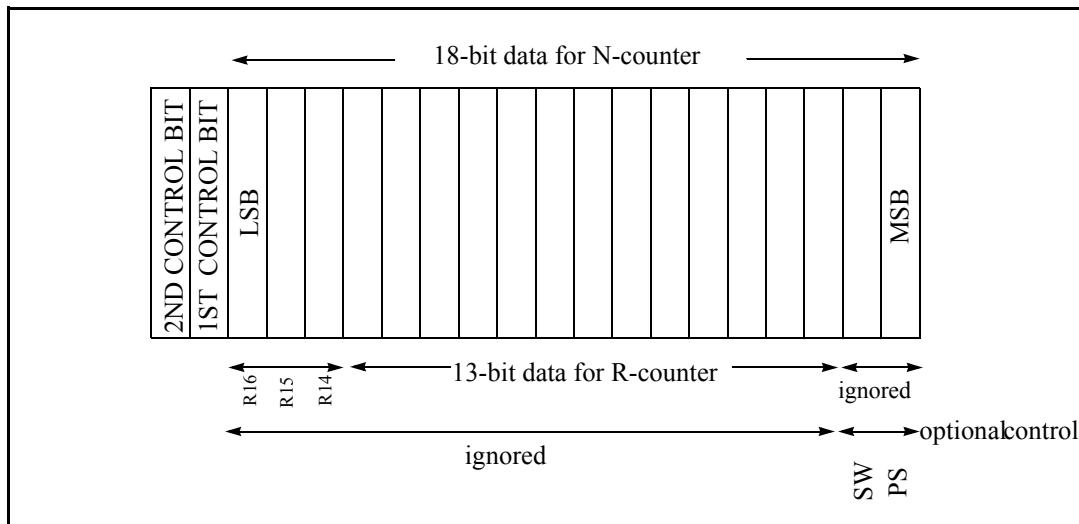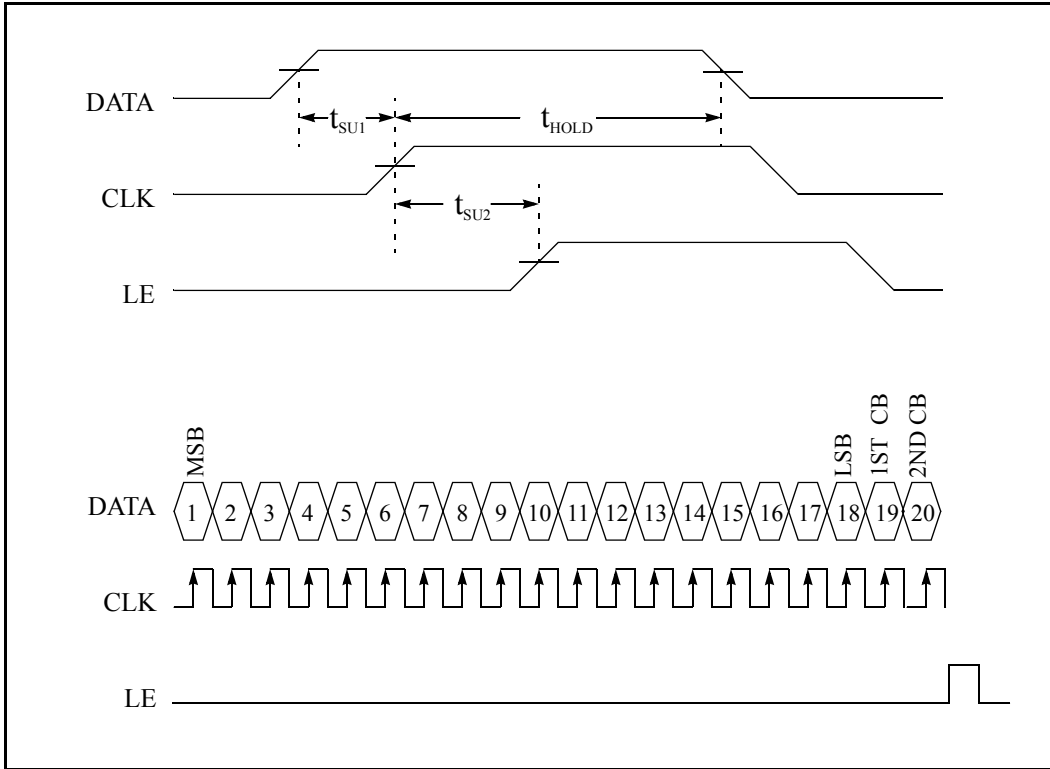
Fig. 1 – Serial input data format

Table 1: Control Bit Setting

1st CB	2nd CB	Fetching Target of Serial Data Input
X	0	N-counter
0	1	PS and SW
1	1	R-counter

Fig. 2 – Serial input data timing waveforms

DATA

t_{SU1} t_{HOLD}

CLK

t_{SU2}

LE

DATA   MSB   LSB 1ST CB 2ND CB
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20

CLK

LE

Phase/Frequency Detector (PFD)

The PFD compares an internal input frequency divider output signal, f_V, with an internal reference frequency divider output signal, f_R, and generates an error signal, DO, which is proportional to the phase error between f_V and f_R. The DO output is intended for use with a passive filter as shown in Fig. 2.

Lock Detector (LD)

When phase comparator detects phase difference, LD terminal outputs "L". When phase comparator locks, LD terminal outputs "H". On standby, outputs "H". The criteria for lock condition is that the phase difference between f_V and f_R is less than *2/xin* and continues for more than three consecutive times.

The input/output waveforms for the PFD and LD are shown in Fig. 3.

Fig. 2 – Passive low-pass filter circuit
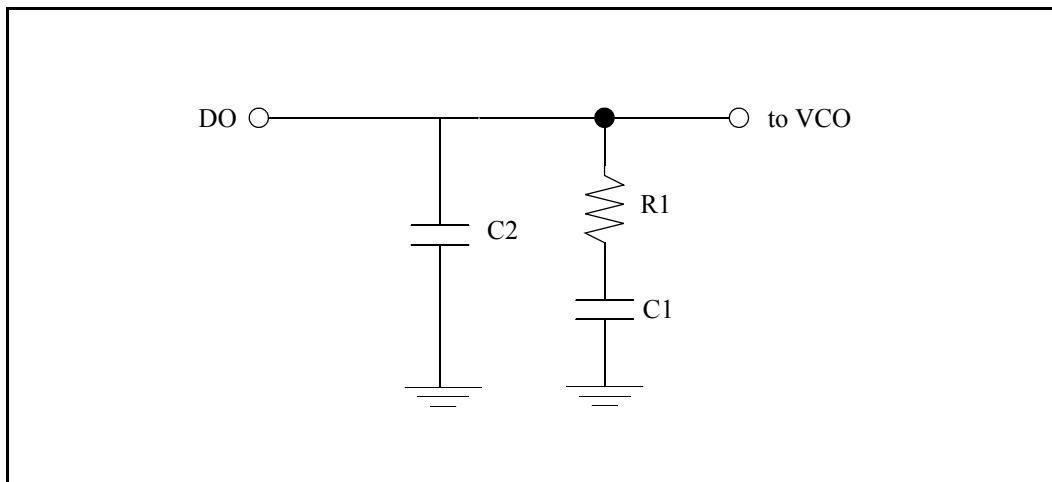
Fig. 3 – PFD input/output waveforms
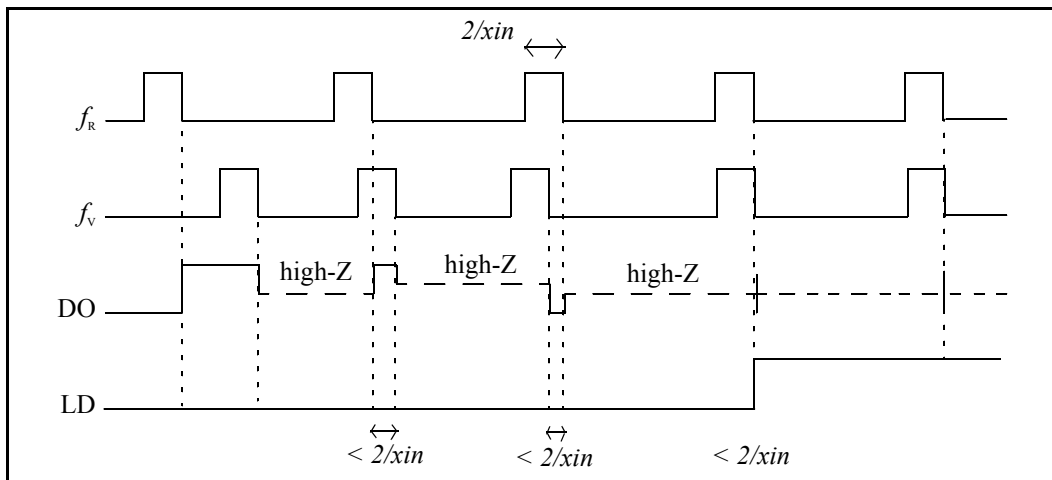
Stand-by Mode

The stand-by mode for the PLL is entered by programming the PS bit to high. In the stand-by mode, the XIN and FIN amplifiers, *N*-counter, and *R*-counter are stopped, as well as the internal current bias for charge pump block, the *N*- and *R*-counters are also reset, and the DO and DB outputs are set to the high impedance state. As long as voltage is supplied to V_{DD2}, data loaded to the latches is kept. To exit from stand-by mode to normal operation, the PS bit must be programmed to low.

Reference Crystal Oscillator Buffer Output (BO)

This IC provides a reference crystal oscillator buffer output intended to be used as a crystal local oscillator to a 2nd mixer. The terminal is represented as BO. For cases to enhance the buffer output swing, increasing V_{DD1} will be an efficient way.

**Filter Switch Control (SW)**

Control of SW terminal by "SW" bit. This terminal is for switching time-constant of loop filter. Output type of this terminal is open drain output. When constant of loop filter doesn't change by this switch, general open drain output is available. Note that there is an internal 200Ω resistor connected between and drain terminal and output pin.
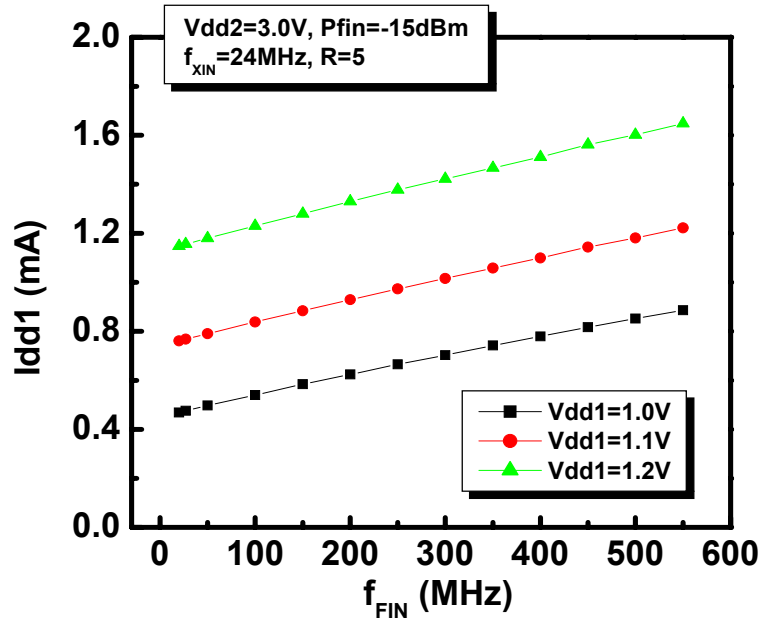
Application Circuit
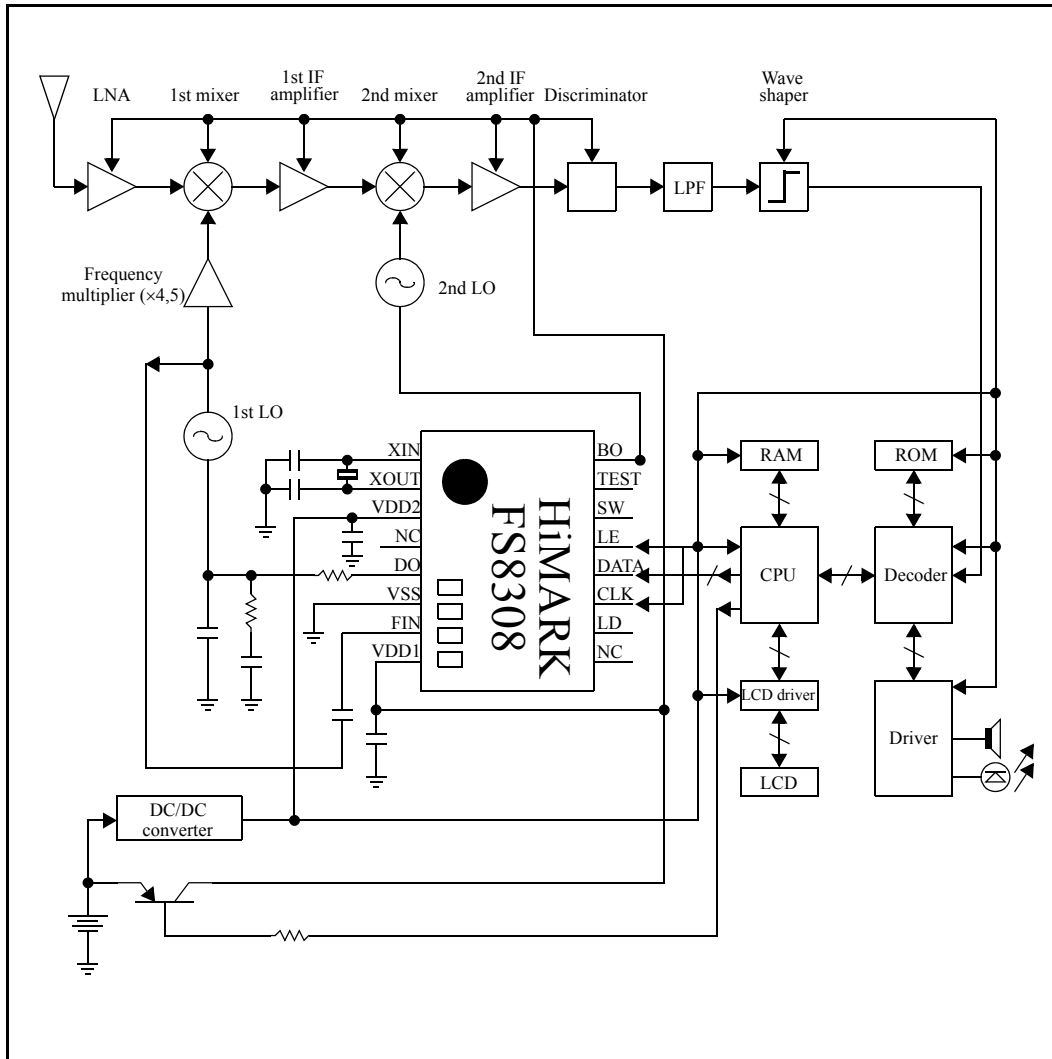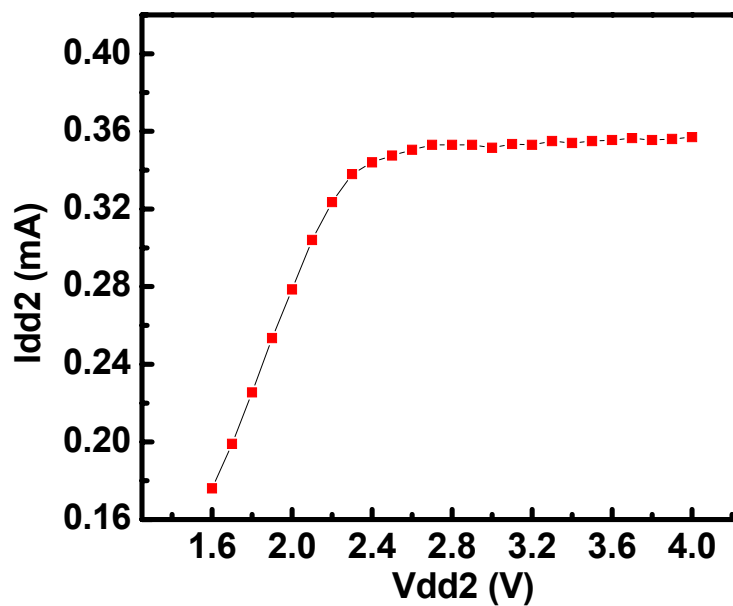
Typical Characteristics
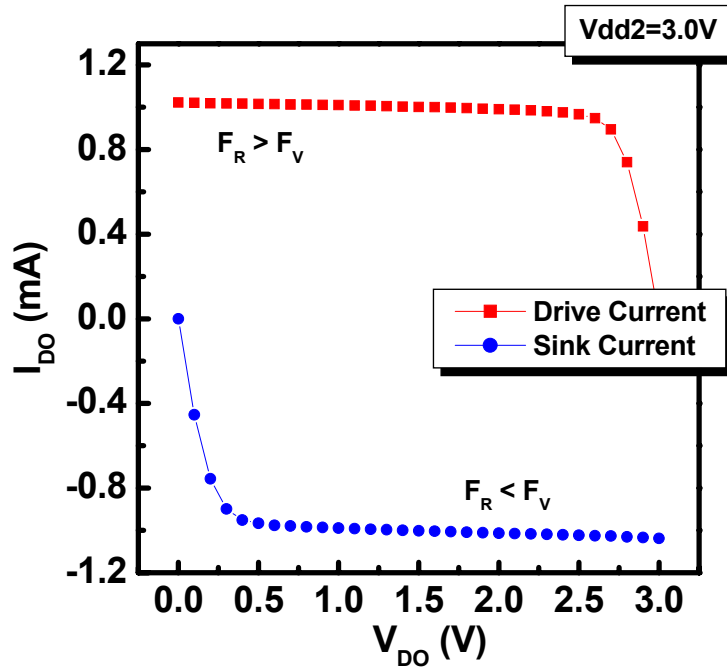
FIN Input Sensitivity vs. Input Frequency
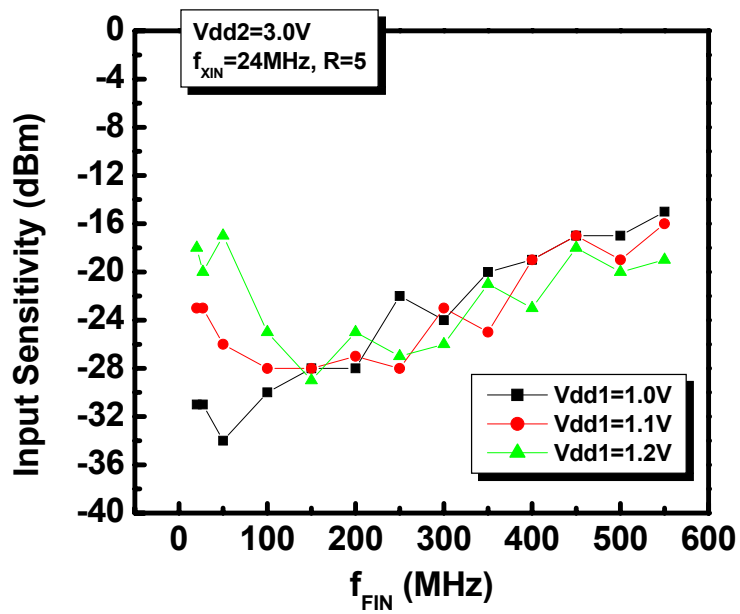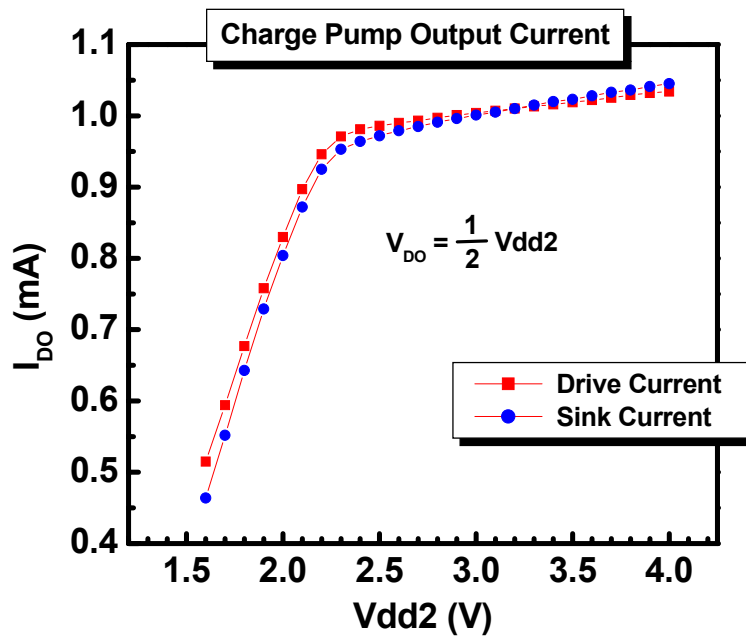
Current Consumption of Idd1 vs. Operating Frequency

Vdd2=3.0V, Pfin=-15dBm
f_{XIN}=24MHz, R=5

- Vdd1=1.0V
- Vdd1=1.1V
- Vdd1=1.2V

Current Consumption of Idd2 vs. Supply Voltage Vdd2

Charge Pump Output Characteristics

Vdd2=3.0V

$F_R > F_V$

$F_R < F_V$

Drive Current
Sink Current

I_{DO} (mA)

V_{DO} (V)

Charge Pump Output Current vs. Power Supply Voltage

Charge Pump Output Current

$V_{DO} = \frac{1}{2}$ Vdd2

Drive Current
Sink Current

I_{DO} (mA)

Vdd2 (V)

Single Voltage Operation

This IC requires two separate power supplies to operate. If only one voltage source is available, ex. use battery to serve as power source, the user can apply the configuration as shown in the following which is referred to as single voltage operation.
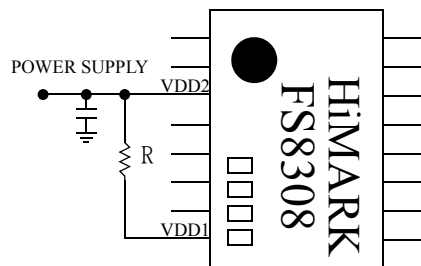
Since there is only one voltage source provided in the so-called single voltage configuration, which is directly connected to V_{dd2}, one needs to choose a reasonable R value to set V_{dd1} to operate within the safe region, whose requirement is $V_{dd1} > 0.95V$. Keep in mind that the lower V_{dd1} is, the less current this IC will consume, but the poorer crystal buffer output it drives. In order to balance the trade-off between the current consumption and crystal buffer driving capability, V_{dd1} is suggested to be about 1.1V. V_{dd1} vs. V_{dd2} for various R at *fin=470MHz* is plotted in the following figure. Note that although smaller resistor R makes this IC consume more current, the reward is with wider power supply input range. Typical value of R is recommended to be around *1.6KΩ.*.

Single Voltage Characteristic: Vdd1 vs. Vdd2 for Various R